Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HP 5800-48G-PoE+ Switch w 2 Intf Slts(JC101B)
HP 5820X-14XG-SFP+ Switch w 2 Intf Slts(JC106B)
HP 5800-48G-PoE+ TAA Sw w 2 Slots(JG242B)
HP 5820X-14XG-SFP+ TAA Switch w 2 Slots(JG259B)
HP A5800-48G-PoE+ Switch with 2 Interface Slots（JC101A）
HP A5820X-14XG-SFP+ Switch with 2 Interface Slots（JC106A）
HP A5800-48G-PoE+ TAA-compliant Switch with 2 Interface Slots（JG242A）
HP A5820X-14XG-SFP+ TAA-compliant Switch with 2 Interface Slots & 1 OAA Slot（JG259A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on FAN-ASSEMBLY 2, and then remove FAN-ASSEMBLY 2.
3. Unscrew the screws on card 3, and then remove card 3.
4. Unscrew the screws on card 4, and then remove card 4.
5. Unscrew the screws on power 5, and then remove power 5.
6. Unscrew the screws on filler panel 6, and then remove filler panel 6.
7. Unscrew the screws on filler panel 7, and then remove filler panel 7.
8. Unscrew the screws on filler panel 8, and then remove filler panel 8.
9. Unscrew the screws on card 9, and then remove card 9.
10. Unscrew the screws on filler panel 10, and then remove filler panel 10.
11. Unscrew the screws on panel 11, and then remove panel 11.
12. Unscrew the screws on cover 12, and then remove cover 12.
13. Unscrew the screws on bracket 13, and then remove bracket 13.
14. Unscrew the screws on PCB 14, and then remove PCB 14.
15. Remove all of the labels.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

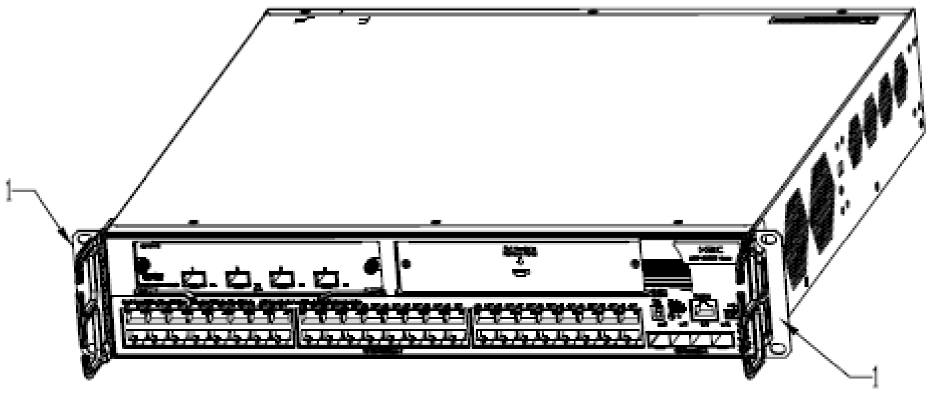

Figure 1Remove mounting angle

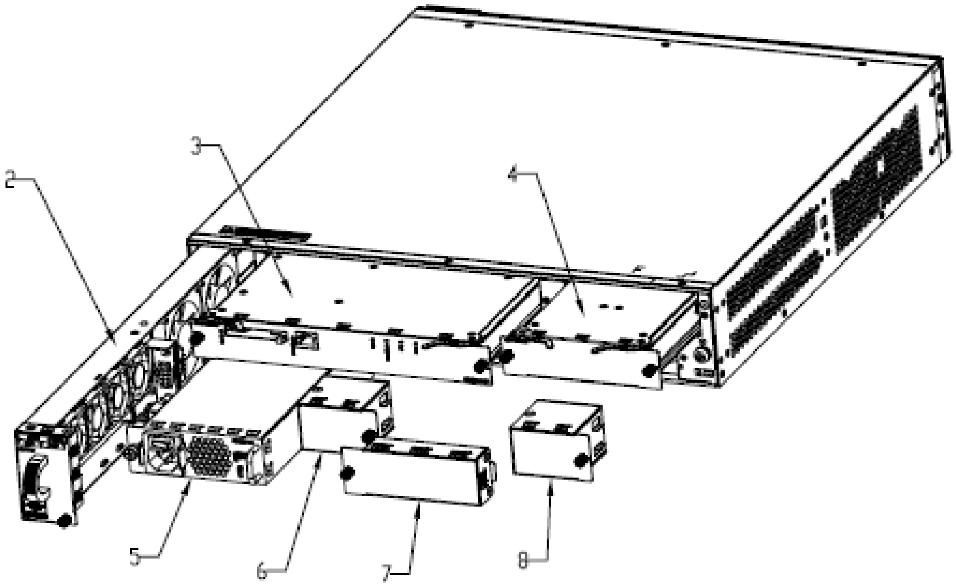

Figure 2 Rear of the product

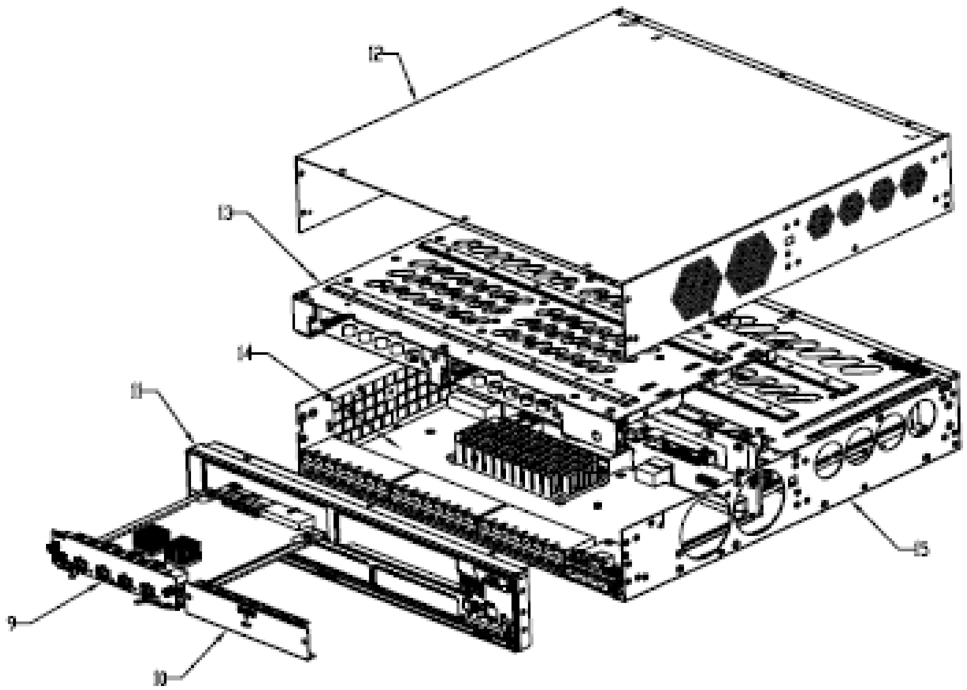

Figure 3 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	162	1.0%		Fe recycling
2		Complex PCB	770	4.8%	The surface of PCB is greater than 10 square centimeters;	
3		Complex PCB	1210	7.5%	The surface of PCB is greater than 10 square centimeters;	
4		Complex PCB	790	4.9%	The surface of PCB is greater than 10 square centimeters;	
5		Complex PCB	940	5.9%	The surface of PCB is greater than 10 square centimeters;	
6		Fe	342	2.1%		Fe recycling
7		Fe	97	0.6%		Fe recycling
8		Fe	342	2.1%		Fe recycling
9		Complex PCB	650	4.0%	The surface of PCB is greater than 10 square centimeters;	
10		Fe	67	0.4%		Fe recycling
11		PC	41	0.3%		PC recycling
12		Fe	2105	13.1%		Fe recycling
13		Fe	1532	9.5%		Fe recycling
14		Complex PCB	1610	10.0%	The surface of PCB is greater than 10 square centimeters;	
15		Fe	5397	33.6%		Fe recycling

4.0 Revised record

Date	Version	Author	Modify content
2014.11.20	V0	Wu Xuejun	Initial version